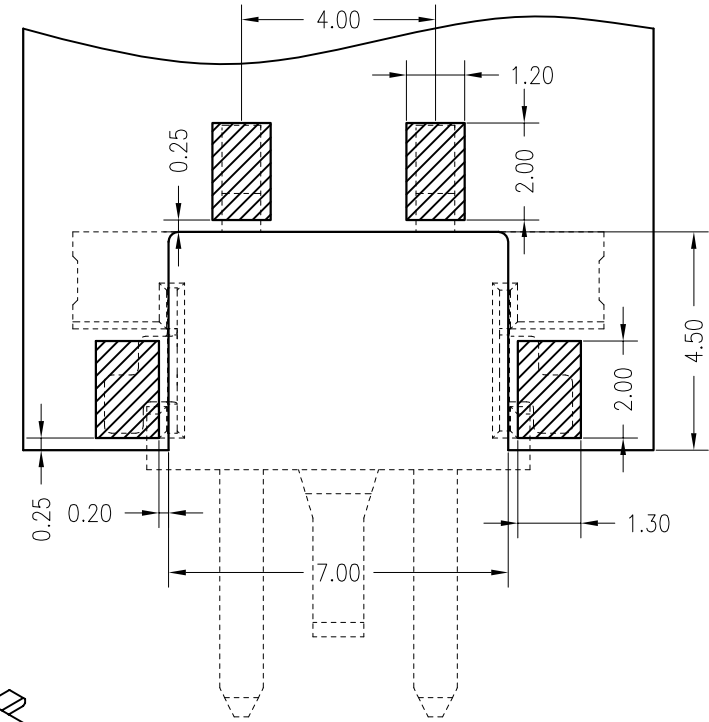
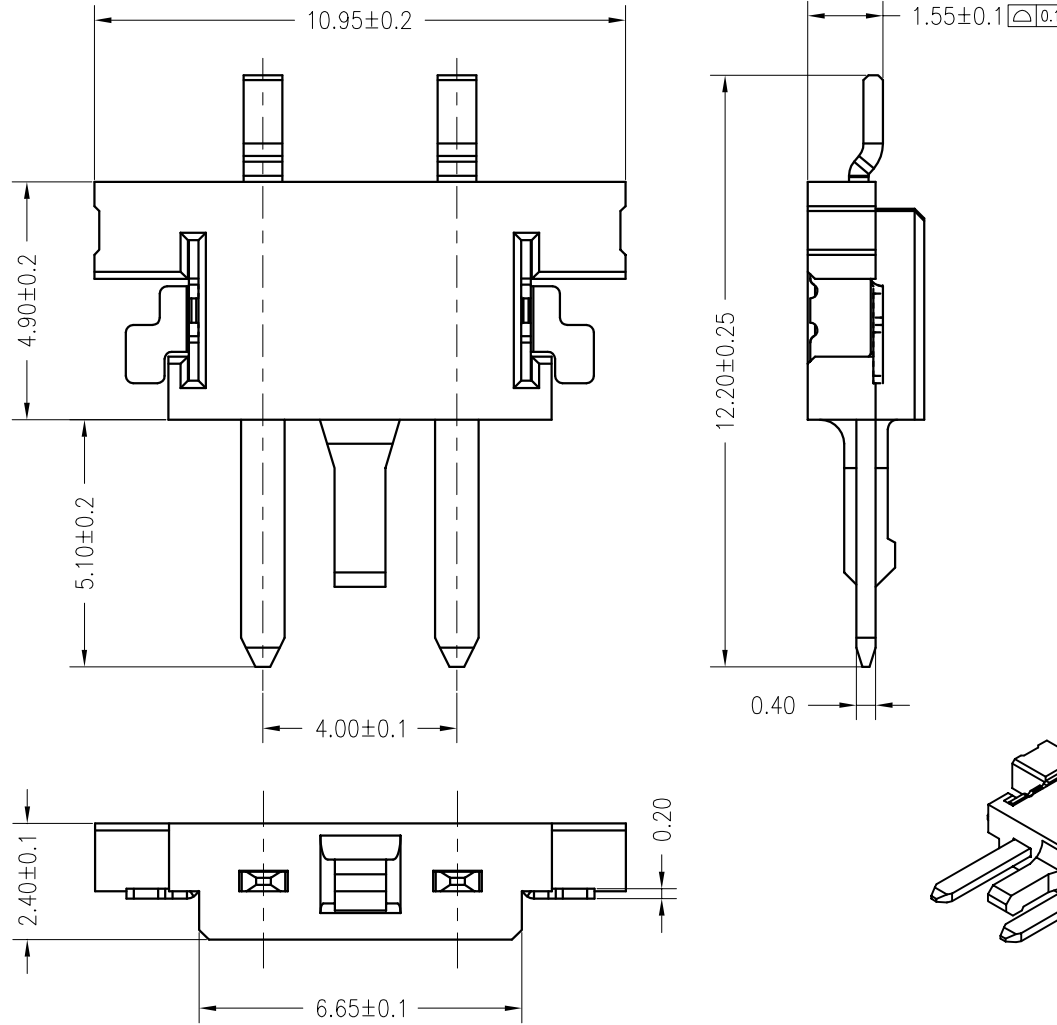
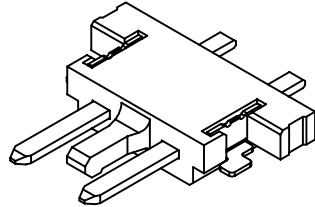
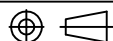


REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	—	2017.03.23



Board Layout



C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE SN
B	CONTACT	2 PCS	PhosphorBronze	MATTE SN
A	HOUSING	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
 東莞市高迪電子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD TITLE: 4.0 板对板 WAFER SMT TYPE				
X.±0.5	X.±5°	USE:	CUSTOMER	
.X±0.3	.X±2°	APPD:	邵敬和	
.XX±0.25	.XX±1°	CHKD:	田峰	
--	--	DR:	蒋建银	
		UNITS:	mm	
			SCALE	SHEET
			1 : 1	1 / 1

主要技术参数 Main Specifications

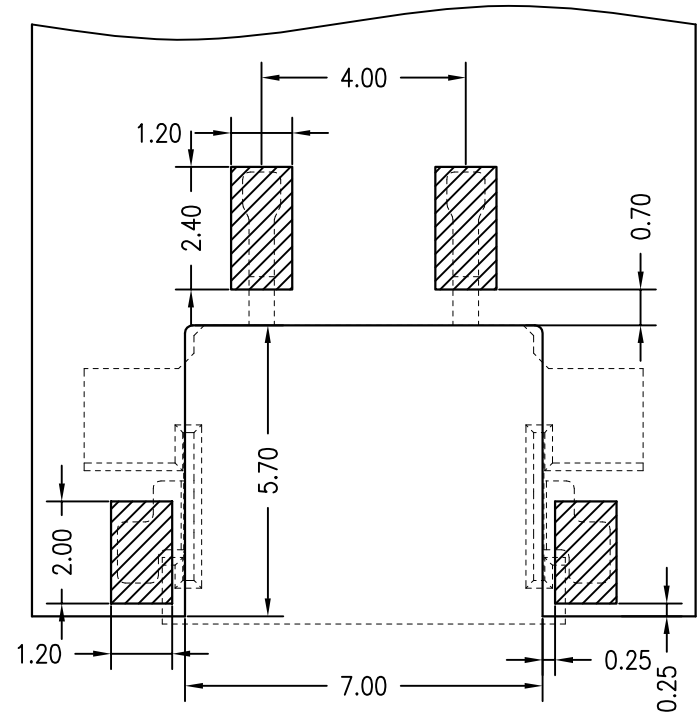
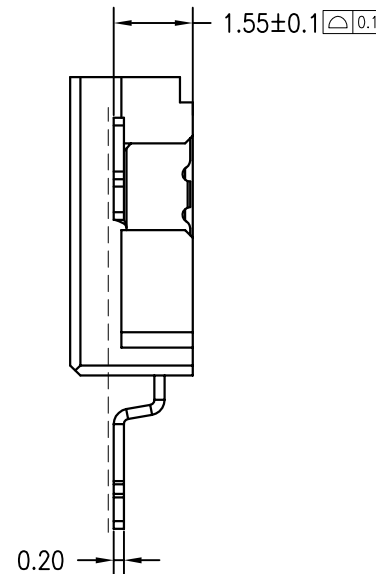
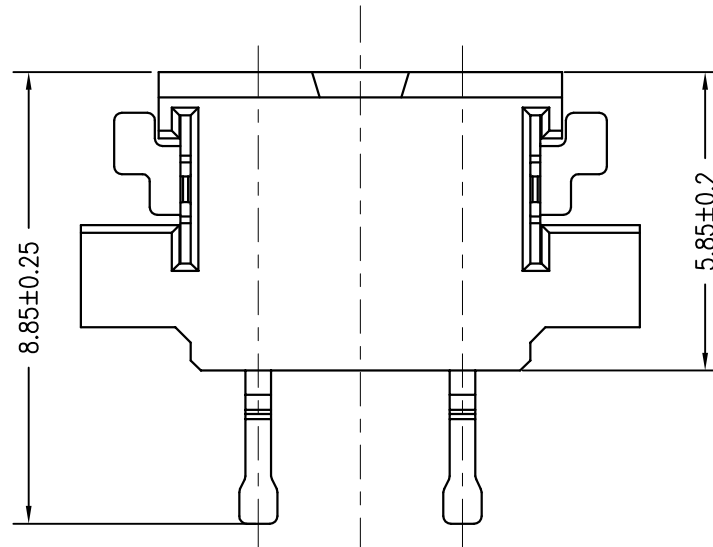
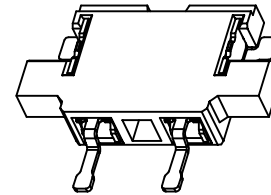
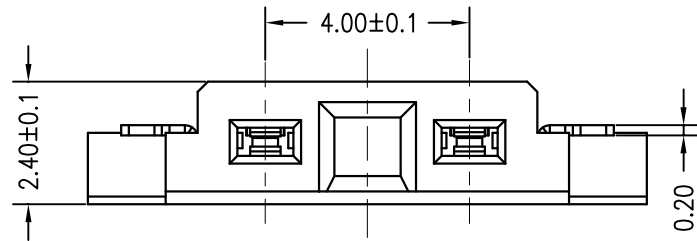
线 数 (Poles): 02
接触电阻 (Contact resistance): ≤30mΩ
绝缘电阻 (Insulation resistance): ≥1000MΩ
额定电压 (Rated voltage): 400V AC DC
额定电流 (Rated current): 1.0A AC DC
耐 电 压 (Withstand Voltage): 1800V AC/minute
温度范围 (Temperature Range): -25℃~ +85℃

ORDER INFORMATION:

PART No.		PACKAGING:	
No.OF CIRCUITS:		P=PEEL	
02		Metal code:	
PLASTIC MATERIAL:		1=PhosphorBronze	
F4M=LCP(BEIGE)		PLATING:	
		B=MATTE Sn	

B4001P-02-F4MB1-R

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	—	2017.03.23

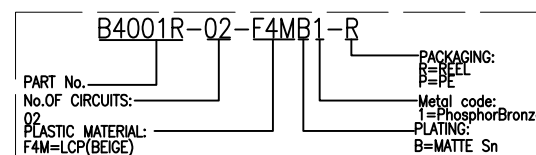


Board Layout

主要技术参数 Main Specifications

线 数 (Poles): 02
 接触电阻 (Contact resistance): $\leq 30m\Omega$
 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
 额定电压 (Rated voltage): 400V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐 电 压 (Withstand Voltage): 1000V AC/minute
 温度范围 (Temperature Range): $-25^{\circ}C \sim +85^{\circ}C$

ORDER INFORMATION:



C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE SN
B	CONTACT	2 PCS	PhosphorBronze	MATTE SN
A	HOUSING	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
東莞市高迪電子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				
TITLE: 4.0 板对板 WAFER SMT TYPE				PART NO.: B4001R-02-F4MB1-R
USE: CUSTOMER				DWG NO.: CCP-0749
APPD: 邵敬和				SCALE 1 : 1
CHKD: 田峰				SHEET 1 / 1
DR: 蒋建银				
X.±0.5 X.±5°		UNITS: mm		
.X±0.3 .X±2°				
.XX±0.25 .XX±1°				
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